

1.10mm Height 0805 Package Bi-Color (Multi-Color) Chip LED Technical Data Sheet

Part No.: DL-PCB0805SRPGC

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Features:

- 1. Package in 8mm tape on 7" diameter reel.
- 2. Compatible with automatic placement equipment.
- 3. Compatible with infrared and vapor phase reflow solder process.
- 4. 2.00mm×1.80mm SMT LED, 1.10mm thickness.
- 5. Low power consumption.
- 6. Color: Hyper Red & Pure Green.
- 7. Bi-color type.
- 8. The product itself will remain within RoHS compliant Version.

Descriptions:

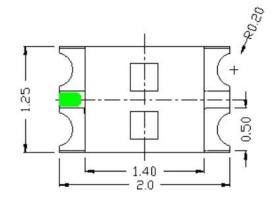
- 1. The PCB 0805 SMD Taping is much smaller than lead frame type components, thus enable smaller higher packing density, reduced storage space and finally smaller equipment to be obtained.
- 2. Besides, light Weight makes them ideal for miniature applications, etc.

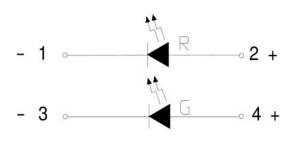
♦ Applications:

- 1. Automotive: Backlighting in dashboard and switch.
- 2. Telecommunication: Indicator and backlighting in telephone and fax.
- 3. Flat backlight for LCD, switch and symbol.

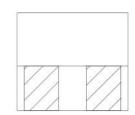
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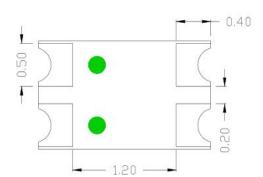
◆ Package Dimension:

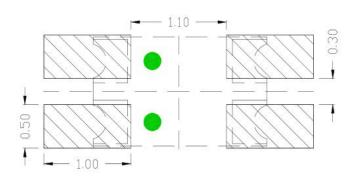












Part No	Chip Material		Lens Color	Source Color
DL-PCB0805SRPGC	SR	AlGaInP	Motor Cloor	Hyper Red
	PG	InGaN	Water Clear	Pure Green

Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ±0.10mm (.004") unless otherwise noted.
- 3. Specifications are subject to change without notice.

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lacktriangle Absolute Maximum Ratings at Ta=25 $^{\circ}$ C

Parameters		Symbol	Max.	Unit	
Payer Dissipation	Hyper Red	PD	60	mW	
Power Dissipation	Pure Green	טי	95		
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)		IFP	100	mA	
Continuous Forward Current		IF	25	mA	
Reverse Voltage		VR	5	V	
Operating Temperature Range		Topr	-40°C to +80°C		
Storage Temperature Range		Tstg	-40°C to +85°C		
Soldering Temperature		Tsld	260℃ for 5 Seconds		

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Parameters	Symbol	Emitting Color	Min.	Тур.	Max.	Unit	Test Condition	
	IV	Hyper Red	100	170			IF=20mA	
Luminous Intensity		Pure Green	200	320		mcd	(Note 1)	
Viewing Angle	20	Hyper Red		120			IF=20mA	
Viewing Angle	2θ _{1/2}	Pure Green	130			Deg	(Note 2)	
Dook Emission Woyalangth) n	Hyper Red		632		nm	Measurement @Peak	
Peak Emission Wavelength	λр	Pure Green		520		nm		
Dominant Wavelength	λd	Hyper Red		624		nm	IF=20mA (Note 3)	
		Pure Green		525				
Spectral Line Half-Width	Δλ	Hyper Red		20		nm	IF=20mA	
Spectral Line Hall-Width		Pure Green		35		11111		
Forward Voltage	VF	Hyper Red	1.60	2.00	2.40	V	IF=20mA	
		Pure Green	2.80	3.40	3.80	V		
Reverse Current	IR	Hyper Red			10	μА	V _R =5V	
	IIV	Pure Green						

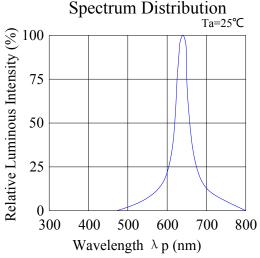
Notes:

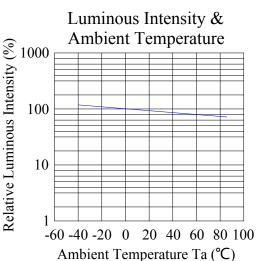
- 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
 - 2. $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength (λd) is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

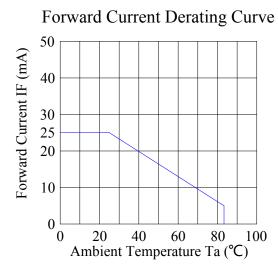
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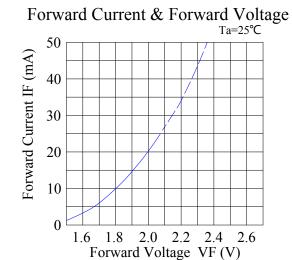
◆ Typical Electrical / Optical Characteristics Curves						
(25 ℃ Ambient Temperature Unless Otherwise Noted)						
Hyper Red:						

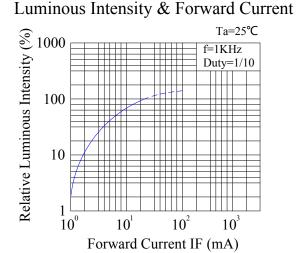
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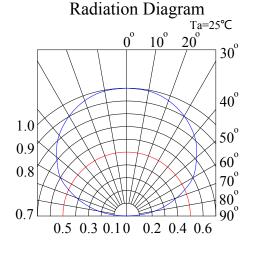




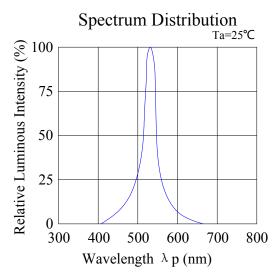


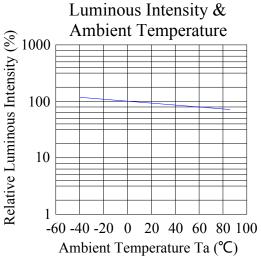


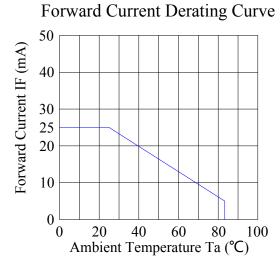


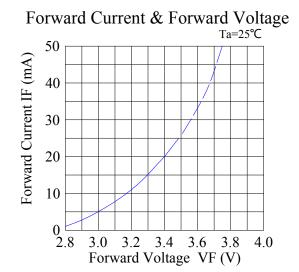


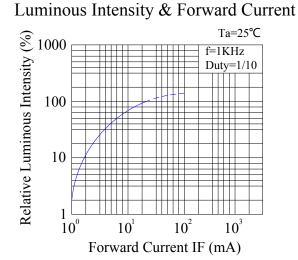
Pure Green:

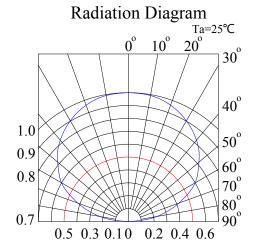












Reliability Test Items And Conditions:

The reliability of products shall be satisfied with items listed below:

Confidence level: 90%.

LTPD: 10%.

1) Test Items and Results:

No.	Test Item	Test Hours/Cycles	Test Conditions	Sample Size	Ac/Re
1	Resistance to Soldering Heat	6 Min	Tsld=260±5℃, Min. 5sec	25pcs	0/1
2	Thermal Shock	300 Cycles	H: +100°C 5min ∫ 10 sec L: -10°C 5min	25pcs	0/1
3	Temperature Cycle	300 Cycles	H: +100°C 15min ∫ 5min L: -40°C 15min	25pcs	0/1
4	High Temperature Storage	1000Hrs.	Temp: 100°C	25pcs	0/1
5	DC Operating Life	1000Hrs.	IF=20mA	25pcs	0/1
6	Low Temperature Storage	1000Hrs.	Temp: -40℃	25pcs	0/1
7	High Temperature/ High Humidity	1000Hrs.	85℃/85%RH	25pcs	0/1

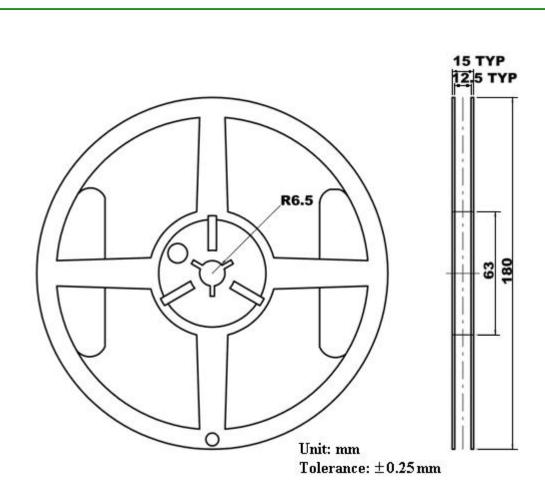
2) Criteria for Judging the Damage:

ltem	Symbol	Test Conditions	Criteria for Judgment		
		rest Conditions	Min	Max	
Forward Voltage	VF	IF=20mA		F.V.*)×1.1	
Reverse Current	IR	VR=5V		F.V.*)×2.0	
Luminous Intensity	IV	IF=20mA	F.V.*)×0.7		

^{*)} F.V.: First Value.

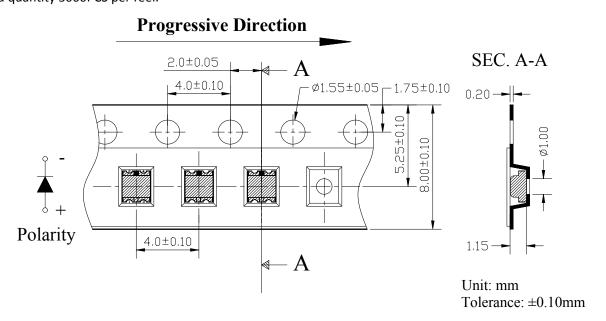
♦ Reel Dimensions:

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Carrier Tape Dimensions:

Loaded quantity 3000PCS per reel.



Please read the following notes before using the datasheets:

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1. Over-current-proof

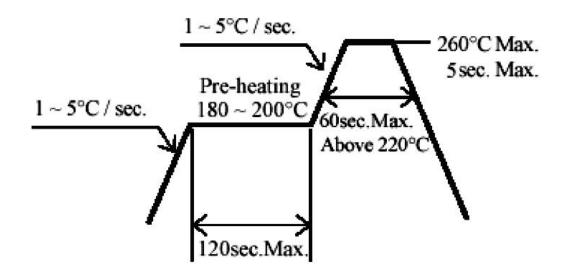
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30℃ or less and 90%RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30 $^{\circ}$ C or less and 70%RH or less.
- 2.5 The LEDs should be used within 168 hours (7 days) after opening the package.
- 2.6 If the moisture adsorbent material (silica gel) has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 60±5 °C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile.



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 260°C for 5 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

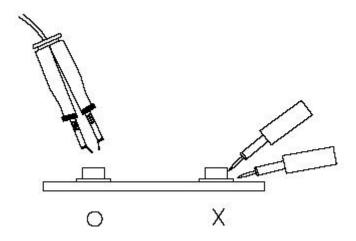
5. Repairing

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Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



6. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

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